

REMARKS/ARGUMENTS

The Office Action mailed August 18, 2008 has been carefully considered. Claims 1, 3 and 5-9 are pending with claims 1 and 8 being in independent form. By the present Amendment, claims 1 and 8 have been amended to further clarify the features of the present application.

Applicant appreciates the courtesy extended to Applicant's attorney, Keith J. Barkaus, during the telephone interview of November 17, 2008. During the telephone interview, the claims of the present application were discussed in conjunction with the references to Hiroshi, Kanno and Harada. Agreement was reached as to language that could be added to the claims in order to distinguish them from the prior art. By the present Amendment, claims 1 and 8 have been amended to include the language that was agreed to during the telephone interview.

Claims 1, 3, and 5-9 stand rejected under 35 U.S.C. 103(a) as allegedly being unpatentable over Japanese Patent Publication No. JP2001-313331 to Hiroshi in view of U.S. Patent No. 6,677,167 to Kanno and U.S. Patent No. 6,771,483 to Harada et al. (hereinafter "Harada"). Reconsideration of this rejection is respectfully requested.

The Examiner argues that Hiroshi disclose many of the features of claim 1, for example, of the present application. The Examiner concedes, however, that Hiroshi does not disclose 1) an insulating sprayed layer having a thickness in a range of 20 μm to 500 μm , 2) a convex fitting section disposed on a peripheral section on either one of the ceramic base body or the temperature controlling section and 3) a concave fitting section disposed on a peripheral section of the ceramic base body or the temperature controlling section so that the convex fitting section and the concave fitting section engage together. The Examiner argues that Kanno discloses a convex part and a concave part on the peripheral section of the ceramic base body referring to the silicon ring 32 and the stepped shape of the edge of susceptor 76. The Examiner argues that it would have been obvious to modify Hiroshi to include these features to provide a way for the ring to mate with the susceptor. The Examiner further argues that Harada discloses an electrostatic chuck with a thickness of 100-500 micrometers and argues that it would be obvious to modify Hiroshi to have an insulation layer 8 with this thickness since this layer must be dense

and of the proper dimension to ensures the properties of electrical insulating, corrosion and resistance to plasma erosion. Applicant respectfully disagrees.

Claim 1, as amended herein, relates to a susceptor device that includes, among other things, “a convex fitting section” and “a concave fitting section disposed on a peripheral section of the ceramic base body or the temperature controlling section so that the convex fitting section and the concave fitting section engage together to completely cover the insulating sprayed layer and the bonding agent layer such that the insulating sprayed layer and the bonding agent layer are protected from external damage.”

As is noted above, the Examiner concedes that Hiroshi does not disclose convex and concave parts and relies on Kanno as allegedly teaching this feature. In Kanno, the wafer stage shown in Figs 1, 6, 11-14, 16, 19 and 20 engages the focus ring. However, the drawings clearly show a space formed between the wafer stage and the focus ring 32, for example, in Fig. 12. The space, which is provided to facilitate changing of the focus ring as it wears down due to exposure to plasma and corrosive gasses allows for invasion of plasma or corrosive gas to reach inner components such as the inner electrodes, the insulative layer and the bonding agent layer. Thus, the susceptor and the ring do not engage each other “to completely cover the insulating sprayed layer and the bonding agent layer such that the insulating sprayed layer and the bonding agent layer are protected from external damage,” as is required by amended claim 1, of the present application. In contrast, the space of Kanno, discussed above, allows for invasion of plasma or corrosive gas to reach inner components including the insulative layer and the bonding agent layer.

In addition, it would not be obvious to further modify Hiroshi to include the features of claim 1 in light of Kanno since the space that is provided between the wafer stage and the focus ring 32 of Kanno is provided to allow for the changing of the focus ring. That is, the space is intentionally provided and necessary for operation of the device of Kanno. Thus, not only does Kanno fail to disclose the features of claim 1 discussed above, but specifically teaches away from them.

Harada also fails to disclose the patentable features of claim 1 described above.

Accordingly, it is respectfully submitted that claim 1, and the claims depending therefrom, are patentable over the cited art for at least the reasons described above.

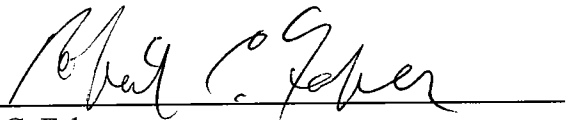
Similarly, with regard to independent claim 8, the cited art fails to disclose a susceptor device including “a convex fitting section disposed on a peripheral section on either one of the ceramic base body or the temperature controlling section” and “a concave fitting section disposed on a peripheral section of the ceramic base body or the temperature controlling section so that the convex fitting section and the concave fitting section engage together to completely cover the insulating sprayed layer and the bonding agent layer such that the insulating sprayed layer and the bonding agent layer are protected from external damage.”

Accordingly, it is respectfully submitted that claim 8 is also patentable over the cited art for at least the reasons described above.

In light of the remarks herein, it is respectfully submitted that claims 1, 3 and 5-9 are patentable over the cited art for at least the reasons described above.

Favorable reconsideration is respectfully requested.

Respectfully submitted,



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